

POWER DISSIPATION (SOT-89)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

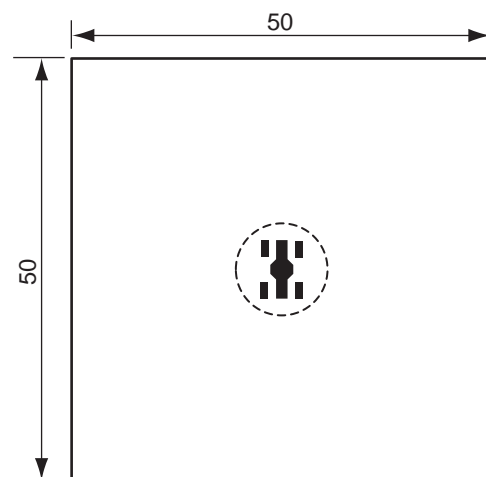
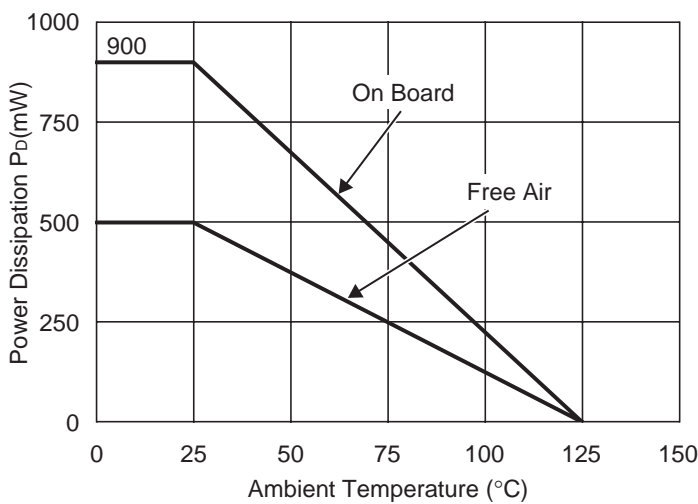
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	50mm × 50mm × 1.6mm
Copper Ratio	Top side : Approx. 10% , Back side : Approx. 100%
Through-hole	-

Measurement Result

($T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$)

	Standard Land Pattern	Free Air
Power Dissipation	900mW	500mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/0.9W=111^{\circ}C/W$	200 $^{\circ}C/W$



Measurement Board Pattern

○ IC Mount Area (Unit : mm)

RECOMMENDED LAND PATTERN (SOT-89)

